

DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR ELECTROLESS PLATING A CONTACT PAD; the specification of which is attached hereto;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: Tongbi Jiang
Inventor's signature
Date 2/17/99
Residence: 12036 West Patrina Drive, Boise, Idaho 83713
Citizenship: People's Republic of China
Post Office Address: same as above
Full name of second inventor: Li Li Inventor's signature
Post Office Address: same as above
Send Correspondence To:

KNOBBE, MARTENS, OLSON & BEAR, LLP

Customer No. 20,995

Application No.: Unknown Filing Date: Herewith



PATENT

Client Code: MICRON.084A

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ASSIGNMENT

WHEREAS, We, Tongbi Jiang, a citizen of the People's Republic of China, residing at 12036 West Patrina Drive, Boise, Idaho 83713 and Li Li, a citizen of the People's Republic of China residing at 2790 North Oldstone Way, Meridian, Idaho 83642, have invented certain new and useful improvements in a METHOD AND APPARATUS FOR ELECTROLESS PLATING A CONTACT PAD for which we have executed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, Micron Technology, Inc. (hereinafter "ASSIGNEE"), a Delaware Corporation, with its principal place of business at 8000 South Federal Way, P.O. Box 6, Boise Idaho 83707-0006, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in return for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

proper patent protection for			resentatives and assigns,	, to obtain and enforce
IN TESTIMONY	WHEREOF, I hereunto se	et my hand and seal thi	s <u>17th</u> day of <u>Feb</u>	19 <u>99</u> .
	·		~ DC	>
		Tongbi Jiang	3	
STATE OF	ij			
COUNTY OF	ss.			
On <u>Feb. 17,</u>	1999, before me,		, personally a	ppeared Tongbi Jiang
personally known to me (or to the within instrument, a signature on the instrument	nd acknowledged to me	that he executed the sa	ame in his authorized ca	apacity, and that by his
num KNEHS Satthan	nd and official seal.	. //		

ary Signature

PATENT

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